PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6513599

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MARIA CLEMENS YPIL QUINONES	01/05/2021
BIGILDIS DOSDOS	12/17/2020
JEROME TEYSSEYRE	01/08/2021
ERWIN IAN VAMENTA ALMARGO	12/23/2020
ROMEL N MANATAD	12/23/2020

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
Street Address:	5005 E. MCDOWELL ROAD
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State/Country:	ARIZONA
Postal Code:	85008

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17248382

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	ONS04025US
NAME OF SUBMITTER:	SHARRON CASTILLO
SIGNATURE:	/Sharron Castillo/
DATE SIGNED:	01/25/2021

Total Attachments: 6
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For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we,

Name	of (City and State OR Country)
MARIA CLEMENS YPIL QUINONES	**CEBU CITY PHILIPPINES**
BIGILDIS DOSDOS	**SAN JOSE, CALIFORNIA US**
JEROME TEYSSEYRE	**SCOTTSDALE, ARIZONA US**
ERWIN IAN VAMENTA ALMAGRO	**LAPU-LAPU CITY PHILIPPINES**
ROMEL N MANATAD	**LILOAN PHILIPPINES**

agree to sell, assign, and transfer, and do hereby sell, assign, and transfer to Semiconductor Components Industries, LLC, a limited liability company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives ("SCI"), the entire right, title, and interest in and to the inventions and discoveries as described, illustrated, and/or claimed in

Title: MOLDED PACKAGING FOR WIDE BAND GAP SEMICONDUCTOR DEVICES
Attorney Docket No.: ONS04025US
Serial No.: 17/248382
Filing Date: January 22, 2021

together with the entire right, title, and interest in and to the above listed application(s), and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, international, foreign, and any and all other applications related thereto, and also including any and all grants, issuances, letters patent, reissues, reexaminations, renewals, priority rights, and priority claims related to any of the foregoing, and any and all rights to collect past damages for infringement of any of the foregoing (the "Patent Rights").

We further authorize SCI to apply for and hold and maintain the Patent Rights throughout the world directly in its own name or any other name which SCI deems appropriate in its sole discretion, and to claim the priority of the filing date of the above listed application(s).

We agree that, when requested, we will, without charge to SCI, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing, maintaining, and enforcing the Patent Rights in any and all countries and for vesting title thereto in SCI or its nominees.

We represent and warrant that we have full right to convey the entire right, title and interest herein sold, assigned, and transferred, and that the Patent Rights hereby conveyed are free from all prior assignment, grant, mortgage, license, or other encumbrance to anyone other than SCI. We covenant and further warrant that we will not convey hereafter any part of the Patent Rights to anyone other than SCI or do any act whatsoever conflicting with this ASSIGNMENT & AGREEMENT.

We hereby authorize SCI or anyone it may properly designate to insert in this ASSIGNMENT & AGREEMENT the filing date and serial number of the above listed application(s) when ascertained. More than one counterpart of this ASSIGNMENT & AGREEMENT may be executed, each of which will be deemed an original.

By (Inventor signature): ______________________
Maria Clemens Ypil Quinones

Signed on this 5th day of January, 2021 ~~2020~~
day month year

By (Inventor signature): Bigildis Dasde

Bigildis Dosdos

Signed on this 17TH day of DECEMBER, 2020
day month year

By (Inventor signature): ______________________

Jerome Teysseyre

Signed on this 8 day of January, ~~2020~~ 2021
day month year

By (Inventor signature): ____________________

Erwin Ian Vamenta Almagro

Signed on this 23rd day of DECEMBER, 2020
day month year

By (Inventor signature): ______________________

Romel N Manatad

Signed on this 23 day of December, 2020
day month year